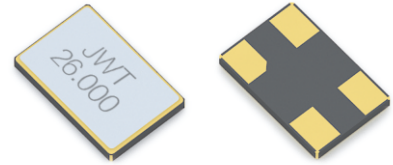


特点 Features

标准的 2.0 x 1.6 x 0.50mm 陶瓷封装表面贴装形式
 小公差、高稳定性及老化率变化小
 适应自动装配的8MM宽度的编带包装
 包装：每卷1000/2000/3000PCS

Typical 2.0 x 1.6 x 0.50 mm Ceramic SMD package
 Tight tolerance and Stability and the annual aging rate changes little
 8mm width Tape&Reel package for automatic assembly
 Packing: Tape & Reel, 1000/2000/3000 pcs per Reel



标准规格 Electronic Specification

型号 Type	SMD2016 (镀金)
频率范围 Frequency Range	16,000 ~ 96,000MHz
振荡模式 Oscillator Mode	Fundamental(AT cut) 基频(AT切)
调整频差 Frequency Tolerance(at25°C)	± 5ppm, ± 10ppm, ± 20ppm
温度频差 Frequency Stability	具体见表2
工作温度 Operating Temperature Range	-40°C ~ 125°C
贮存温度 Storage Temperature Range	-55°C ~ 125°C
负载电容 Load Capacitance	Custom design(8 ~ ∞pF)
激励电平 Drive Level	50 μW Typical (200 μW max.)
静态电容 Shunt Capacitance	5pF max.
老化率 Aging	ΔF/F: ± 1PPM/year(max.)

特殊技术要求可定制

等效电阻 Equivalent Series Resistance(E.S.R.)

频率范围 Frequency Range	盒型 Hold Type	振动模式 Mode	等效电阻 E.S.R.	频率范围 Frequency Range	盒型 Hold Type	振动模式 Mode	等效电阻 E.S.R.
16,000 ~ 19,999MHz	SMD	AT,Fund	150Ω Max	30,000 ~ 54,000MHz	SMD	AT,Fund	80Ω Max.
20,000 ~ 29,999MHz	SMD	AT,Fund	100Ω Max	54,000 ~ 96,000MHz	SMD	AT,Fund	60Ω Max.

Table 1

温度频差和工作温度范围 Frequency Stability Vs Operating Temperature range

Temp.(°C)\ppm	± 5	± 10	± 15	± 20	± 25	± 30	± 50
-10 to 60°C	△	○	○	○	○	○	○
-20 to 70°C		△	○	○	○	○	○
-40 to 85°C			△	○	○	○	○
-40 to 125°C						△	○

○:可实现的 △:与供应商沟通

Table 2

外型尺寸 Outline Dimensions(Unit:mm)

